

#### 30V N-Channel MOSFET

#### **General Description**

The 3006 uses advanced trench technology to provide excellent RDS(ON). This device is suitable for low voltage, high speed switching applications in power supplies.

#### **Features**

- Simple Drive Requirement
- 100% Avalanche tested
- RoHS Compliant

#### **Product Summary**

BVDSS	RDSON	ID
30V	$6.5$ m $\Omega$	90A

#### **Applications**

- DC/DC converter
- Load Switch
- Power Motor Controls
- Bridge Circuits

# TO-220/263/262 Pin Configuration



#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	30	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current <sup>1</sup>	90	Α	
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current <sup>1</sup>	58	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	360	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	169	mJ	
P <sub>D</sub>	Total Power Dissipation <sup>4</sup>	75	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		${\mathbb C}$	
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	$^{\circ}\mathbb{C}$	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient(Steady State) <sup>1</sup>		62	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-case <sup>1</sup>		1.68	°C/W

# CMP3006/CMB3006/CMI3006



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# **Electrical Characteristics (TJ=25℃, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		5	6.5	mΩ
R <sub>DS(ON)</sub>		$V_{GS}$ =4.5V , $I_D$ =10A		6.5	10	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1		2.5	V
1	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V			1	uA
I <sub>DSS</sub>		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V ,TC=55 ℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =10A		14		S
$Q_g$	Total Gate Charge (4.5V)	I <sub>D</sub> =15A		20		
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =15 V		7.5		nC
$Q_gd$	Gate-Drain Charge	V <sub>GS</sub> =4.5V		7		
$T_{d(on)}$	Turn-On Delay Time	V <sub>DD</sub> =15V		10		
Tr	Rise Time	I <sub>D</sub> =15 A		15		ne
$T_{d(off)}$	Turn-Off Delay Time	R <sub>G</sub> =3.3Ω		40		ns
T <sub>f</sub>	Fall Time	V <sub>GS</sub> =10V		12		
C <sub>iss</sub>	Input Capacitance			2200		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		250		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			230		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			90	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	VG-VD-UV , FOICE Current			360	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =30 A , T <sub>J</sub> =25 ℃			1.2	V

#### Note

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqslant~300\text{us}$  , duty cycle  $\leqslant2\%$
- 3.The EAS data shows Max. rating . The test condition is VDD=20V,VGS=10V,L=0.5mH,IAS=26A
- 4.The power dissipation is limited by 150  $\!\!\!\!\!^{\,\circ}$  junction temperature
- 5.The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

This product has been designed and qualified for the counsumer market.

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